

### SPECIFICATIONS:

Insulation Resistance: 1,000MΩ min. at 100V DC  
 Withstanding Voltage: 300V DC for 1min  
 Voltage Rating: 30V DC  
 Current Rating: Signal Pin - 0.5A, Power Pin - 1.0A  
 Contact Resistance: 20mΩ max. at 20mV max.  
 Operating Temp.: -40°C ~ +85°C MAX  
 Insertion Force: 40N MAX  
 Mating Cycle: 100 times

### PART NUMBER:

**CNU109S-040-0001**



### MATERIALS AND FINISH:

- Contacts: Cu Alloy
- Solder Pad: Cu Alloy
- Insulator & Over mold: LCP

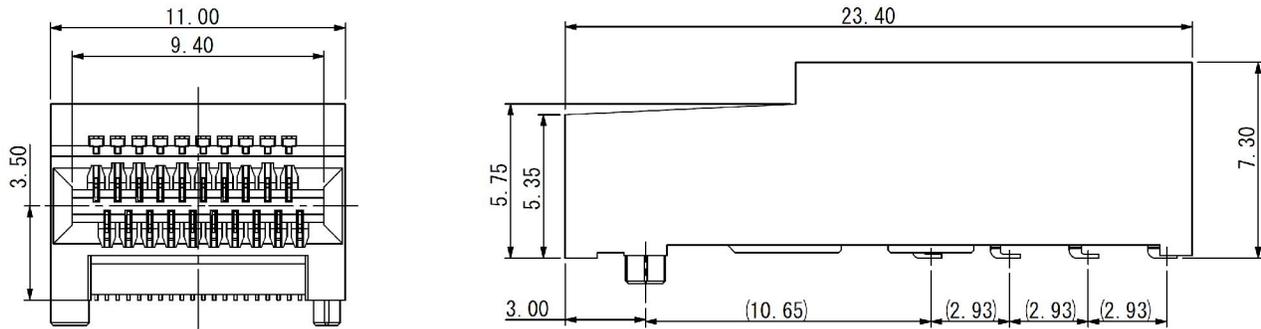
**SFP-DD MSA COMPLIANT**



### FEATURES:

- SFP-DD MSA Design Guideline Compliant
- Supports signals:
  - Supports 25G-NRZ and 56G-PAM4 modulation, providing solutions up to 112G-PAM4
  - Double density with 2 high-speed signal lanes
  - Backward compatibility with current SFP modules

### OUTLINE DIMENSIONS:



### RECOMMENDED PC BOARD LAYOUT:

